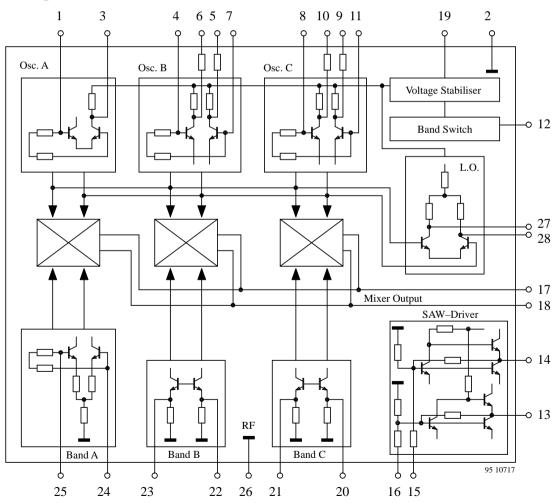
# **TV-Tuner-IC with Three Separate Oscillators and Mixers, SAW-Driver, L. O.-Output and Tri-State Band Switch**

#### Features

- 9 V supply voltage
- Frequency range from 48 to 860 MHz
- Band A: balanced high impedance mixer input and amplitude controlled oscillator
- Band B + C: balanced low impedance mixer input and symmetrical oscillator
- Balanced L. O.-outputs for prescalers or PLL

- SAW filter driver with low impedance output
- Voltage regulator for stable operating characteristics
- ESD protection on all pins except oscillator pins and RF-inputs

Package: SO-28



#### Figure 1. Block diagram pinning of U2309B

### **Block Diagram**

### **Pin Configuration**

		Pin	Symbol	Function
Osc A, base $1$	28 L.O. out	1	Osc A, base	Oscillator band A, base
	27 L.O. out	2	GND	Ground, common
GND (common) 2	27 L.O. out		(common)	
		3	Osc A, coll.	Oscillator band A, collector
Osc A, coll. 3	26 GND (RF)	4, 7	Osc B, base	Oscillator band B, bases
		5,6	Osc B, coll.	Oscillator band B, collectors
Osc B, base 4	25 RF in, A	8, 11	Osc C, base	Oscillator band C, bases
		9, 10	Osc C, coll.	Oscillator band C, collectors
Osc B, coll. 5	24 RF in, A	12	Band sw.	Tri-state band switch
Osc B, coll. 6	23 RF in, B	13, 14	SAWF, out	SAW filter driver outputs
		15, 16	SAWF, inp.	SAW filter driver inputs
Osc B, base 7	22 RF in, B	17, 18	Mix out	Mixer outputs, open collec-
				tor
Osc C, base 8	21 RF in, C	19	Vs	Supply voltage V <sub>s</sub>
		20, 21	RF in, C	RF inputs, band C
Osc C, coll. 9	20 RF in, C	22, 23	RF in, B	RF inputs, band B
		24, 25	RF in, A	RF inputs, band A
Osc C, coll. 10	19 V <sub>S</sub>	26	GND (RF)	Ground, RF part
		27, 28	L.O. out	L.Ooutputs
Osc C, base 11	18 Mix out			
Band sw. 12	17 Mix out			
SAWF, out 13	16 SAWF, inp.			
SAWF, out 14	15 SAWF, inp.			
95	10886			

### **Absolute Maximum Ratings**

All voltages are referred to GND, Pin 2

Parameters		Symbol	Min.	Тур.	Max.	Unit
Supply voltage	Pin 19	Vs			10.5	V
RF inputs	Pin (20-25)				5.0	V
IF outputs	Pin 17-18				10.5	V
Tri-state switch voltage	Pin 12	ViTRI			10.5	V
Junction temperature		T <sub>i</sub>			125	°C
Storage temperature		T <sub>stg</sub>	-40		125	°C

### **Operating Range**

All voltages are referred to GND, Pin 2

Parameters	Test Conditions / Pins	Symbol	Min	Тур	Max	Unit
Supply voltage	Pin 17-19	Vs	8.1	9	9.9	V
Ambient temperature		T <sub>amb</sub>	-25		75	°C
Thermal resistance	Test conditions p. 6					
	Package SO28	R <sub>thJA</sub>		70		K/W

### **Electrical Characteristics**

Test conditions (unless otherwise specified):  $V_s = 9$  V.  $T_{amb} = 25$  °C. Reference point Pin 2

Parameters	Test Conditions / Pins	Symbol	Min	Тур	Max	Unit
Supply voltage	Pin 17-19	Vs	8.1	9.0	9.9	V
Supply current	Pin 17-19	IS		42	50	mA
Band switch						
Voltage Band A	Pin 12	VSWA	0	0	1.0	V
Voltage Band B	Pin 12	VSWB	1.6	2.0	2.4	V
Voltage Band C	Pin 12	VSWC	3.4	4.0	5.0	V
Switching current	VSW = 5 V Pin 12	ISW			100	μΑ
L. Ooutput						
L. O. level each output	RL = 50 Ohm Pin 27, 28	PLO	-25		-17	dBm
<b>SAW filter driver</b> fi = 36 M	Hz					
Input impedance	Pin 15, 16	ZiSAW		450		Ohm
Output impedance	Pin 13, 14	ZoSAW		70		Ohm
Voltage gain	$Pin 15, 16 \rightarrow 13, 14$	GvSAW		17		dB
Band A						
Input frequency range	Pin 24	fiA	48		170	MHz
Input impedance	Figure 3 Pin 24	S11A				
Gain (note 4)	Pin I/P to O/P	GA		28		dB
Noise figure DSB (note 2)	Pin I/P to O/P					
	fiA = 50 MHz	NF		11.5		dB
	fiA = 150 MHz	NF		12		dB
Input level for (note 3):	Each carrier					
IM3 (interm. of 3rd order	fiA = 71 MHz Pin I/P	ViA		-23		dBm
IM2 (interm. of 2nd order)	fiA = 71 MHz Pin I/P	ViA		-22		dBm
Band B (note 1)		1	1	1	1	
Input frequency range	Pin 22, 23	fiA	170		470	MHz
Input impedance	Figure 3 Pin 22, 23	S11B				
Gain (note 4)	Pin I/P to O/P	GB		32		dB
Noise figure DSB (note 2)	Pin I/P to O/P					
	fiB = 200  MHz	NF		9.5		dB
	fiB = 450  MHz	NF		10		dB
Input level for (note 3):	Each carrier					
IM3 (interm. of 3rd order)	fiB = 300  MHz Pin I/P	ViB		-28		dBm

### TEMIC N EFLINKEN Semiconductors

Parameters	Test Conditions / Pins		Symbol	Min	Тур	Max	Unit
Band C (note 1)							
Input frequency range		Pin 20, 21	fiC	470		860	MHz
Input impedance	Figure 3	Pin 20, 21	S11C				
Gain		Pin I/P to O/P	GC		32		dB
Noise figure DSB (note 2)	Pin I/P to O/P						
	fiC = 500 MHZ		NF		10.5		dB
	fiC = 800 MHz		NF		11.5		dB
Input level for (note 3):	Each carrier						
IM3 (interm. of 3rd order)	fiC = 600 M	Hz Pin I/P	ViC		-28		dBm

#### Notes

<sup>1)</sup> The RF inputs B and C are symmetrical driven by means of a hybrid for  $180^{\circ}$  phase shifting, consequently the source impedance is  $100 \Omega$ . All other impedance for RF tests is  $50 \Omega$ .

<sup>2)</sup> The noise figure (NF) is the value for double-side-band measurement.

<sup>3)</sup> The intermodulation test (2-carrier-method) which is made on IF-centre is in reference to a signal-to-IM ratio of 60 dB.

<sup>4)</sup> Gain is the ratio of the voltage at the primary coil of L5 to the available voltage at the input.

### **Test and Principle Application Circuit**

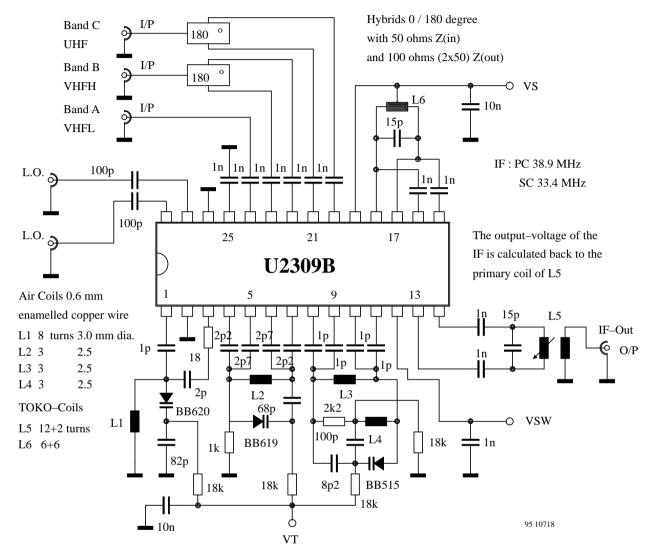


Figure 2. Test and principle application circuit

### PCB for the R<sub>thJA</sub>-Measurement

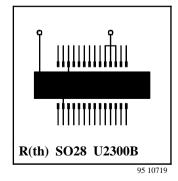


Figure 3. PCB for the  $R_{thJA}$ -measurement

### Input Impedance Mixer Band A (S11A), B and C (S11B/C)

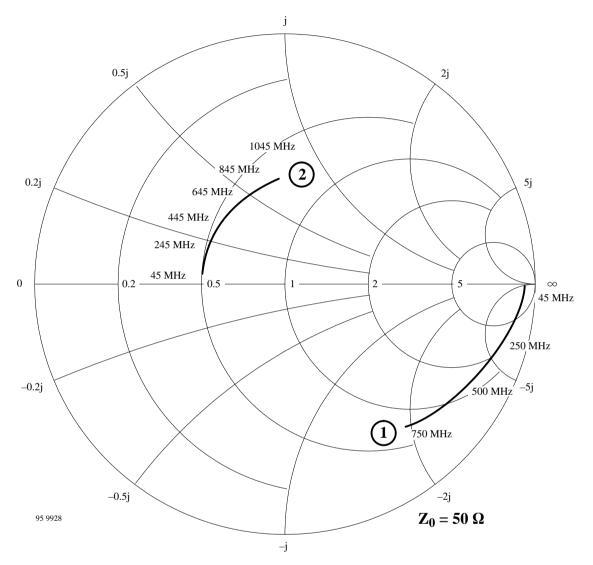


Figure 4. Input impedance mixer band A (S11A), B and C (S11B/C)

#### 1) VHF-low

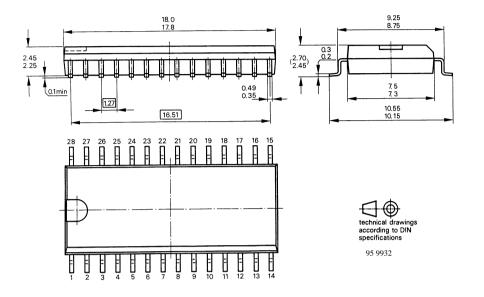
Normalised to 50  $\Omega$ , measuring range 45 MHz to 750 MHz.

#### 2) VHF-high and UHF

Normalised to 50  $\Omega$ , measuring range 45 MHz to 1045 MHz. Both inputs are driven symmetrical. The output impedance of hybrid is 100  $\Omega$ , the measured levels are then calculated in reference to 50  $\Omega$ .



### **Dimensions in mm:**



### **Ozone Depleting Substances Policy Statement**

It is the policy of TEMIC TELEFUNKEN microelectronic GmbH to

- 1. Meet all present and future national and international statutory requirements.
- 2. Regularly and continuously improve the performance of our products, processes, distribution and operating systems with respect to their impact on the health and safety of our employees and the public, as well as their impact on the environment.

It is particular concern to control or eliminate releases of those substances into the atmosphere which are known as ozone depleting substances (ODSs).

The Montreal Protocol (1987) and its London Amendments (1990) intend to severely restrict the use of ODSs and forbid their use within the next ten years. Various national and international initiatives are pressing for an earlier ban on these substances.

**TEMIC TELEFUNKEN microelectronic GmbH** semiconductor division has been able to use its policy of continuous improvements to eliminate the use of ODSs listed in the following documents.

- 1. Annex A, B and list of transitional substances of the Montreal Protocol and the London Amendments respectively
- 2. Class I and II ozone depleting substances in the Clean Air Act Amendments of 1990 by the Environmental Protection Agency (EPA) in the USA
- 3. Council Decision 88/540/EEC and 91/690/EEC Annex A, B and C (transitional substances) respectively.

**TEMIC** can certify that our semiconductors are not manufactured with ozone depleting substances and do not contain such substances.

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